

S48	13	("Re31967" "2893315" "3301730" "3437522" "3448516" "3480836" "4087300" "4354895" "4694572" "4982495" "4997517" "5025114" "5065228").PN.	USPAT	OR	ON	2003/09/26 10:20
S49	10	"3448516".URPN.	USPAT	OR	ON	2003/09/26 10:21
S50	112	ink\$1jet and flexible adj tape	USPAT; EPO; JPO	OR	ON	2003/09/26 10:24
S51	30	"5442386".URPN.	USPAT	OR	ON	2003/09/26 12:10
S52	13	flexible.ti. and (leu).in.	US-PGPUB; USPAT	OR	ON	2004/12/31 15:12
S53	5	("6652068" "6431686" "20030058311" "6409312" "6712457" "6735865").PN.	USPAT; EPO; JPO	OR	ON	2004/12/31 15:33
S54	5	("5748209" "6334660" "6409312" "6431686" "6585347").PN.	USPAT; EPO; JPO	OR	ON	2004/12/31 15:34
S55	4	("6039889" "5304626" "5946012" "6198067").PN.	USPAT; EPO; JPO	OR	ON	2004/12/31 16:05
S56	202	flexible near3 (film layer substrate tape board) same conductive near3 (trace line) with (hole via aperature open\$3)	USPAT; EPO; JPO	OR	ON	2004/12/31 16:07
S57	63	S56 and polymer	USPAT; EPO; JPO	OR	ON	2004/12/31 16:07
S58	1	"6072236".pn.	USPAT; EPO; JPO	OR	ON	2005/01/05 11:22
S59	1	"6309915".pn.	USPAT; EPO; JPO	OR	ON	2005/01/05 11:20
S60	1	"5408738".pn.	USPAT; EPO; JPO	OR	ON	2005/01/05 11:21
S61	1	"6735865".pn.	USPAT; EPO; JPO	OR	ON	2005/01/05 11:22
S62	0	("4323593,5266996,6080668,6042894").pn.	USPAT; EPO; JPO	OR	ON	2005/01/05 14:23
S63	0	("4323593, 5266996, 6080668, 6042894").pn.	USPAT; EPO; JPO	OR	ON	2005/01/05 14:23
S64	4	("4323593", "5266996", "6080668", "6042894").pn.	USPAT; EPO; JPO	OR	ON	2005/01/05 14:36
S65	1	"5266446".pn.	USPAT; EPO; JPO	OR	ON	2005/01/05 14:36
S66	26	(polyimide flexible) near3 (insulat\$4 dielectric) near3 (film tape layer board substrate) and conductive near2 (trace line) and photo\$1polymer	USPAT; EPO; JPO	OR	ON	2005/01/05 17:19

S67	3	("5112462" "5137791" "5364707").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/05 16:49
S68	3	("5112462" "5137791" "5364707").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/05 16:50
S69	5	("5709979").URPN.	USPAT	OR	ON	2005/01/05 16:50
S70	5	polyimide near3 (film tape layer board substrate) and conductive near2 (trace line) and photo\$1polymer and solder near3 mask	USPAT; EPO; JPO	OR	ON	2005/01/05 17:22
S71	5	polyimide with (film tape layer board substrate) and conductive near2 (trace line) and photo\$1polymer and solder near3 mask	USPAT; EPO; JPO	OR	ON	2005/01/05 17:22
S72	50	polyimide with (film tape layer board substrate) and photo\$1polymer and solder near3 mask	USPAT; EPO; JPO	OR	ON	2005/01/05 17:23